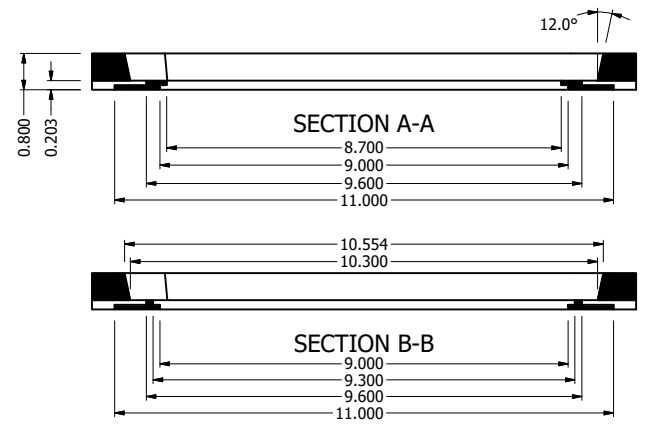
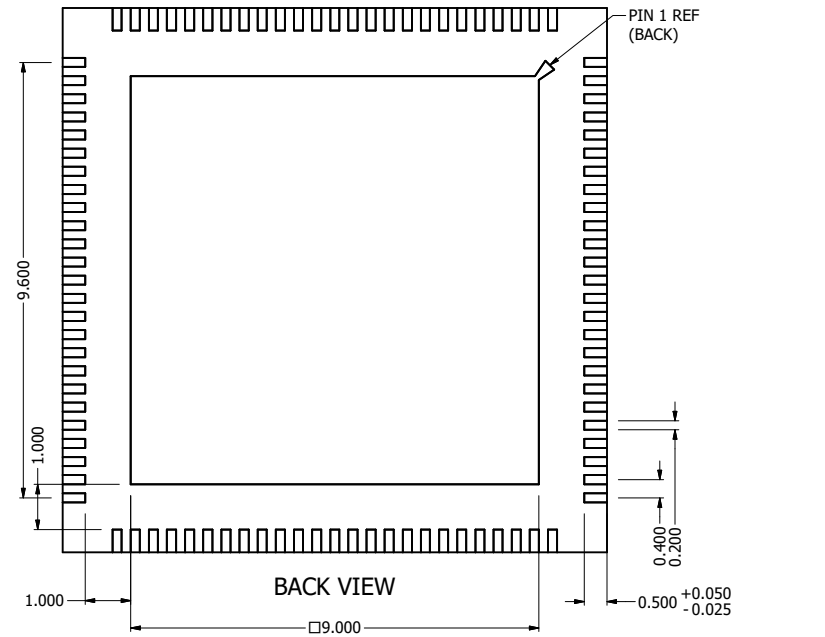
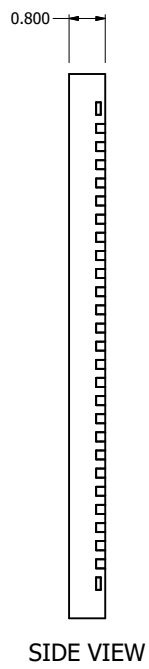
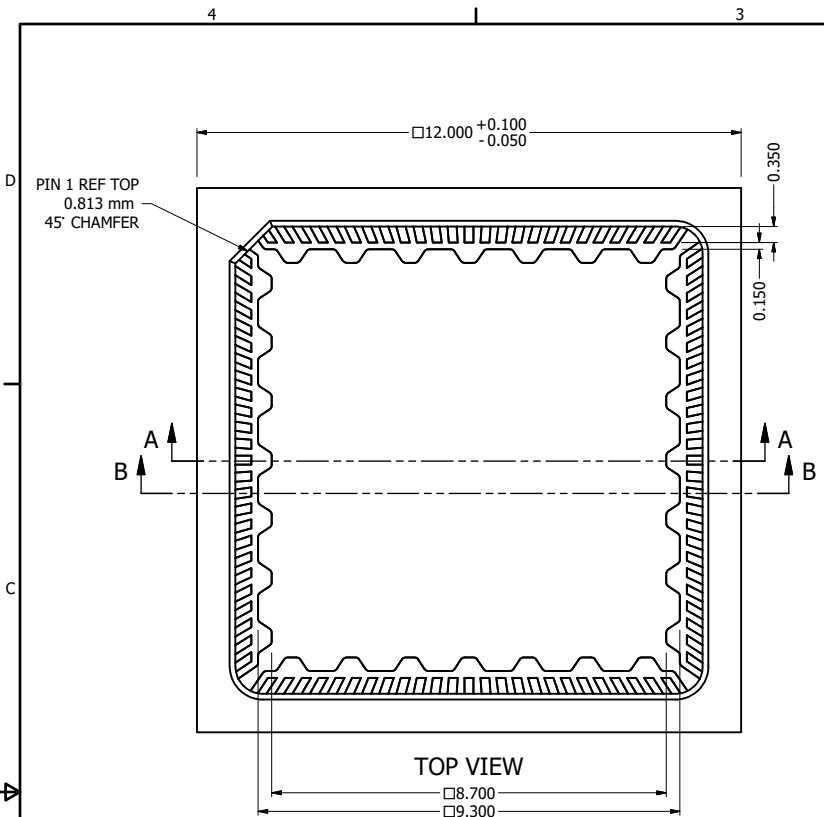
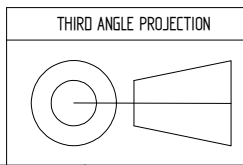


REVISION HISTORY					
ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
	4	11093	RELEASE FOR PRODUCTION	7/2/2009	M.SHELTON
	5	11099	REMODELED FOR A MORE ACCURATE PRINT	1/18/2021	M.SHELTON



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE
 2. LEADFRAME: COPPER, 194 FH
 3. LEAD FINISH: FULL GOLD PLATE
 4. FRAME THICKNESS: 0.203 ± 0.0076
 5. DIE PAD - TOP: 9.300 MAJOR, 8.700 MINOR
 6. DIE PAD - BACK: 9.000
 7. CONFORMS TO JEDEC MO-220



	NAME	DATE
DRAWN	mss	01/19/2021
CHECKED	mss	01/19/2021
ENG APPR	mss	01/19/2021
MGR APPR		

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS
ANGLES ±1°
2 PL ±0.15 3 PL ±0.050



TITLE		
100 LEAD 12mm X 12mm MLP Open-Pak™		
SIZE	DRAWING	REV
A	MLP12X12-100-OP-03-R5	5
FILE NAME: MLP12X12-100-OP-03-R5 ECN11099.dwg		
SCALE: DNS	SHEET 1 OF 1	